



FOR IMMEDIATE RELEASE

New Radiation Tolerant Fast SRAM Memory Product family for Space Applications

Buc, France, April 2010, 2nd - 3D Plus is very pleased to announce the availability of its new Radiation Tolerant Fast SRAM Memory Modules for Space Applications.

Through the successful characterization and qualification of a new 4 Mb SRAM core device, 3D Plus Space Qualified new SRAM Memory Modules are Function – Package - Footprint compatible with our existing modules and they exhibit further enhanced features compared to it:

- High Speed: 12 ns in the -55 °C / +125 °C Temperature Range,
- Single 3.3V Power Supply – Low Power (*5V version is also available*),
- Improved Radiation performance:
 - TID: 100 Krad(Si),
 - SEL: 110 Mev.cm²/mg
 - SEE: 2.17 E-7 error/bit/day (Adams 90 Geosynchronous Orbit without EDAC)
- Worldwide Delivery Guarantee.

These new SRAM modules are available with 4 Mb to 32 Mb memory density and 8-bit to 32-bit data bus width.

They are fully compliant to the 3D Plus Capability Domain qualified by ESA for Space Application and benefit from a full Radiation Assurance Guarantee (TID, SEL and SEE).

"The launch of this new generation of fast radiation tolerant SRAM modules is the conclusion of two years of characterization and space qualification tests including construction analysis, electrical performance test, life tests for long lifetime electronics, reliability as well as TID, SEL and SEE radiation tests" said Pierre-Eric Berthet, 3D Plus Director of Sales and Marketing.

"With 12ns access time over the extended temperature range and the very small package size brought by the 3D stacking technology, our fast Radiation Tolerant SRAM Memory Modules answer the requirements of performance and miniaturization of the most demanding Space qualified Computer boards such as fast 32-bit LEON's processor applications".

"These new devices are now in the hands of our Space customers and will help them to push further the performances of their computer boards for all Space applications fields" added Pierre-Eric Berthet, 3D Plus Director of Sales and Marketing.

Further information:

New Radiation Tolerant Fast SRAM Memory Modules flyers can be down-loaded from 3D Plus website at <http://www.3d-plus.com/product.php?type=1>

The detailed qualification report and the Radiation test (TID, SEL, SEE) reports are available on request at sales@3d-plus.com

The relevant PCN for cross-reference information between new Radiation Tolerant Fast SRAM Memory Modules and the existing ones can be down-loaded from <http://www.3d-plus.com/product-change-notices-2.php>



PRESS RELEASE

About 3D PLUS Company:

Founded in 1996 as a spin-off of Thales, 3D Plus has become a worldwide supplier of advanced high density 3D microelectronic products and die/wafer stacking technology meeting the demand for high reliability, high performance and very small size electronics.

Its patented technology portfolio starts with standard package scale upward to die-size and wafer-level stacking processes. It enables stacking the best standard semiconductor devices and technologies in one single highly miniaturized package with almost no limit for the merging of heterogeneous technologies (bare dice – packages – Passives) and form factors.

3D Plus catalog products and more complex System-In-Package (SiP) solutions bring breakthrough advantages to its customers' electronic designs. They focus on the demand for high-reliability and high-performance for space-saving technology-driven applications in industrial, computing/telecommunications, security and defense, avionics, medical and space markets.

With more than 35 000 modules in Space, and, with a 10 years failure-free Flight Heritage, 3D Plus is the largest Space qualified catalogue products and custom System-In-Packages (SiPs) manufacturer in Europe.

3D Plus products fly in numerous satellite programs for all major space agencies worldwide. Most of the Space missions launched recently, or, to be launched soon embeds 3D Plus Modules. Current customers' portfolio includes the major Aerospace prime contractors and equipment manufacturers spread over more than 30 countries.

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